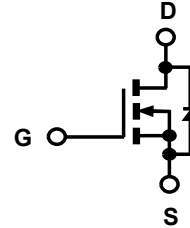


ICE25S65 N-Channel Enhancement Mode MOSFET

Product Summary			
I_D	$T_A=25^\circ\text{C}$	25A	Max
BV_{DSS}	$I_D=250\mu\text{A}$	650V	Min
$r_{DS(on)}$	$V_{GS}=10\text{V}$	0.12 Ω	Typ
Q_g	$V_{DS}=480\text{V}$	34nC	Typ

Features

- Low $r_{DS(on)}$
- Ultra Low Gate Charge
- High dv/dt capability
- High Unclamped Inductive Switching (UIS) capability
- High peak current capability
- Increased transconductance performance
- Optimized design for high performance power systems



TO-263(D²PAK)
1:G, 2:D, 3:S

ICEMOS OWNS THE FUNDAMENTAL PATENTS FOR SUPERJUNCTION MOSFETS. THE MAJORITY OF THESE PATENTS HAVE 17 to 20 YEARS OF REMAINING LIFE. THIS PORTFOLIO HAS GRANTED PATENTS ISSUED IN USA, CHINA, KOREA, JAPAN, TAIWAN & EUROPE.

Maximum ratings^b at $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	25 16.2	A
Pulsed drain current	$I_{D, pulse}$	$T_c=25^\circ\text{C}$	80	A
Avalanche energy, single pulse	E_{AS}	$I_D=8\text{A}$	320	mJ
Avalanche current, repetitive	I_{AR}	limited by T_{jmax}	8	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=480\text{V}$, $I_D=25\text{A}$, $T_j=125^\circ\text{C}$	50.0	V/ns
Gate source voltage	V_{GS}	Static	± 20	V
		AC ($f > 1\text{Hz}$)	± 30	
Power dissipation	P_{tot}	$T_c=25^\circ\text{C}$	245	W
Operating and storage temperature	T_j, T_{stg}		-55 to +150	$^\circ\text{C}$

a When mounted on 1inch square 2oz copper clad FR-4

b limited by T_{jmax}

* Preliminary Data Sheet – Specifications subject to change

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Thermal characteristics

Thermal resistance, junction-case ^a	R_{thJC}		-	-	0.51	°C/W
Thermal resistance, junction-ambient ^a	R_{thJA}	leaded	-	-	62	
Soldering temperature, wave soldering only allowed at leads	T_{sold}	1.6mm (0.063in.) from case for 10 s	-	-	260	°C

Electrical characteristics at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	650	700	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.5	3	3.5	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=650\text{V}, V_{GS}=0\text{V}, T_j=25^{\circ}\text{C}$	-	0.8	1	μA
		$V_{DS}=650\text{V}, V_{GS}=0\text{V}, T_j=150^{\circ}\text{C}$	-	100	-	
Gate source leakage current	I_{GSS}	$V_{GS}=\pm 20\text{ V}, V_{DS}=0\text{V}$	-	-	100	nA
Drain-source on-state resistance	$r_{DS(on)}$	$V_{GS}=10\text{V}, I_D=12.5\text{A}, T_j=25^{\circ}\text{C}$	-	0.120	0.133	Ω
		$V_{GS}=10\text{V}, I_D=12.5\text{A}, T_j=150^{\circ}\text{C}$	-	0.34	-	
Gate resistance	R_G	$f=1\text{ MHz}, \text{open drain}$	-	0.85	-	Ω

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=25\text{V}, f=1\text{ MHz}$	-	1650	-	pF
Output capacitance	C_{oss}		-	234	-	
Reverse transfer capacitance	C_{rss}		-	3	-	
Output capacitance	C_{oss}	$V_{GS}=0\text{ V}, V_{DS}=100\text{ V}, f=1\text{ MHz}$	-	73	-	
Transconductance	g_{fs}	$V_{DS}>2 \cdot I_D \cdot R_{DS}, I_D=12.5\text{A}$	-	23	-	S
Turn-on delay time	$t_{d(on)}$	$V_{DS}=380\text{V}, V_{GS}=10\text{V}, I_D=12.5\text{A}, R_G=4\Omega \text{ (External)}$	-	22.1	-	ns
Rise time	t_r		-	7.4	-	
Turn-off delay time	$t_{d(off)}$		-	46.7	-	
Fall time	t_f		-	2.1	-	

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

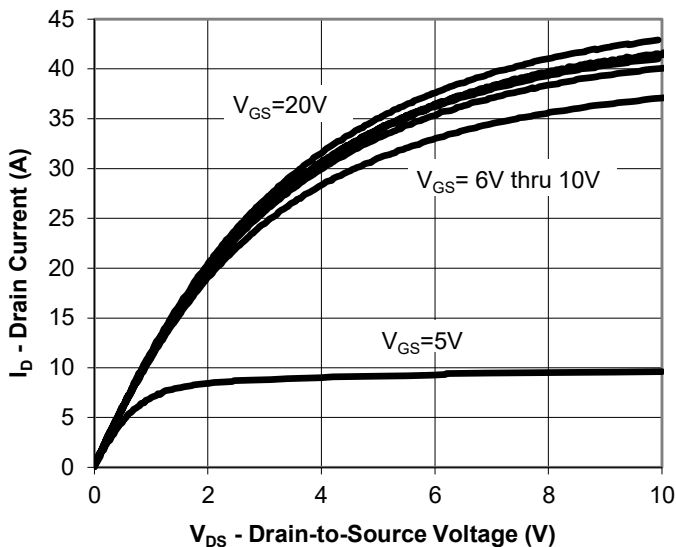
Gate charge characteristics

Gate to source charge	Q_{gs}	$V_{DS}=480\text{ V}, I_D=25\text{ A},$ $V_{GS}=10\text{ V}$	-	7	-	nC
Gate to drain charge	Q_{gd}		-	7	-	
Gate charge total	Q_g		-	34	-	
Gate plateau voltage	$V_{plateau}$		-	5.0	-	V

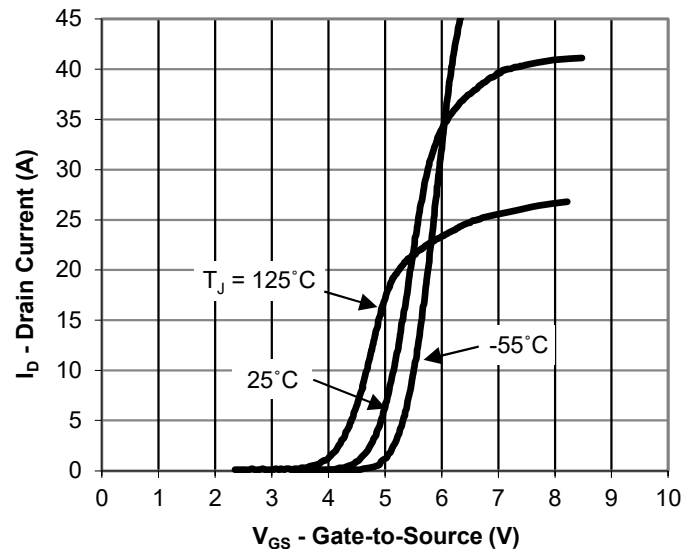
Reverse Diode

Continuous forward current	I_S	$V_{GS}=0\text{ V}$	-	-	25	A
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_S=I_F$	-	1.0	1.2	V
Reverse recovery time	t_{rr}	$V_{RR}=50\text{ V}, I_S=I_F,$ $d_i/d_t=100\text{ A}/\mu\text{S}$	-	326	-	ns
Reverse recovery charge	Q_{rr}		-	5.6	-	μC
Peak reverse recovery current	I_{rm}		-	38	-	A

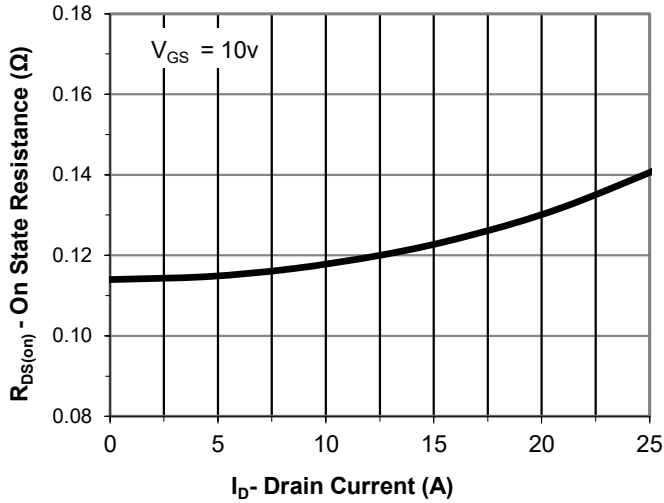
Output Characteristics



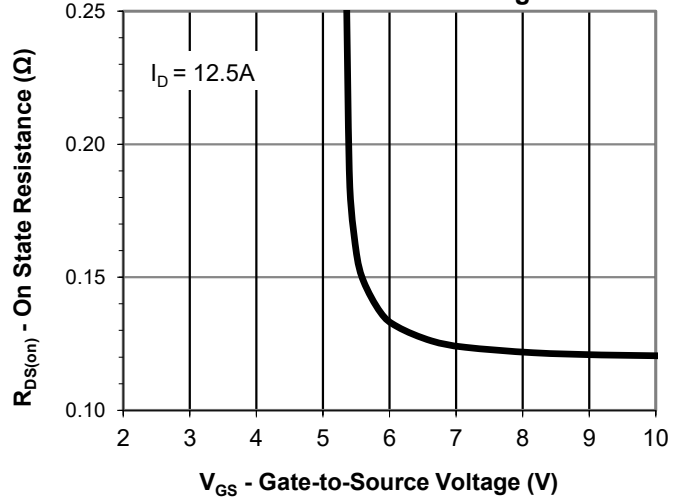
Transfer Characteristics



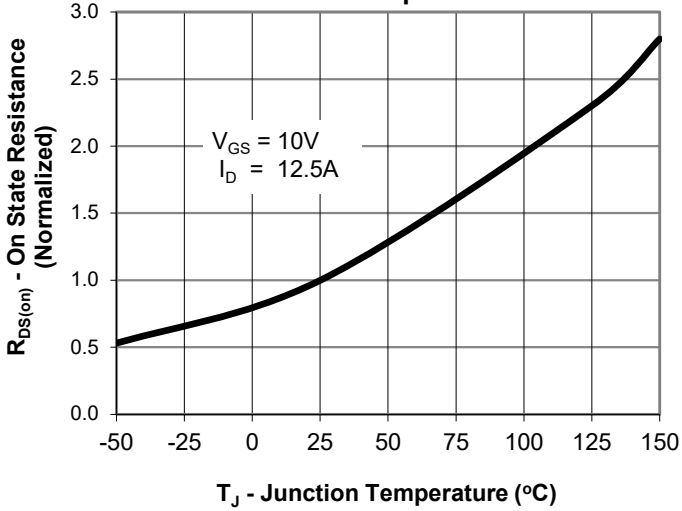
Drain-Source On-State Resistance vs. Drain Current



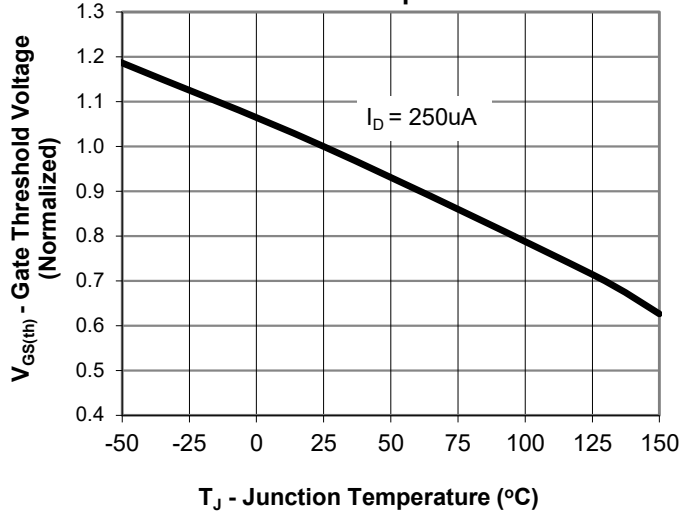
Drain-Source On-State Resistance vs. Gate-to-Source Voltage



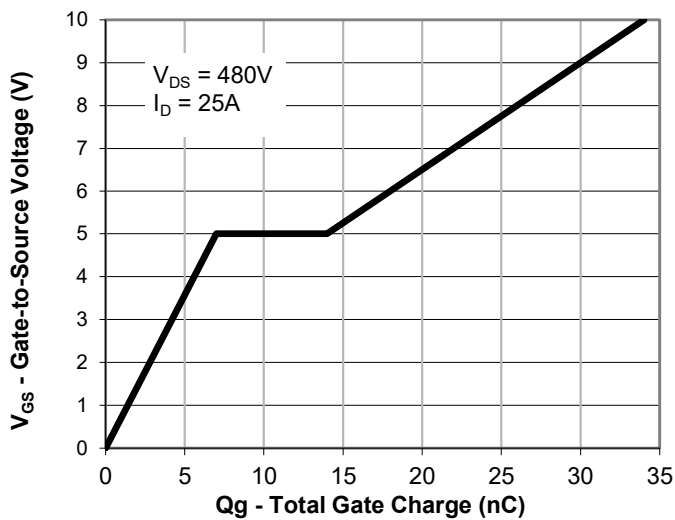
Drain-Source On State Resistance vs. Junction Temperature



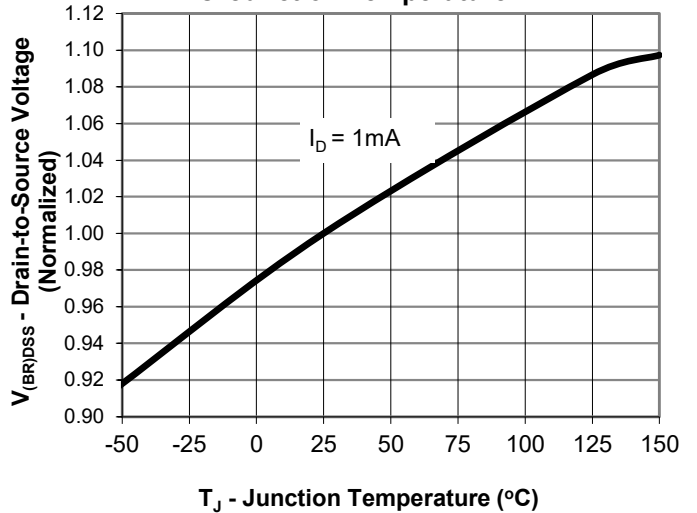
Gate Threshold Voltage vs. Junction Temperature



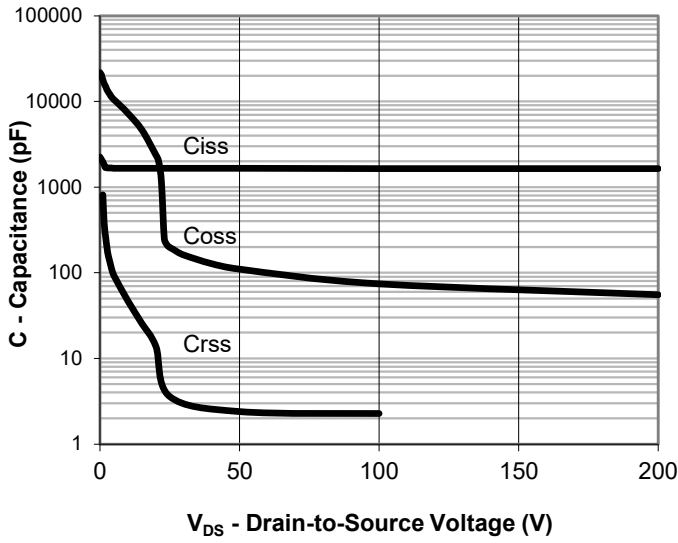
Gate Charge



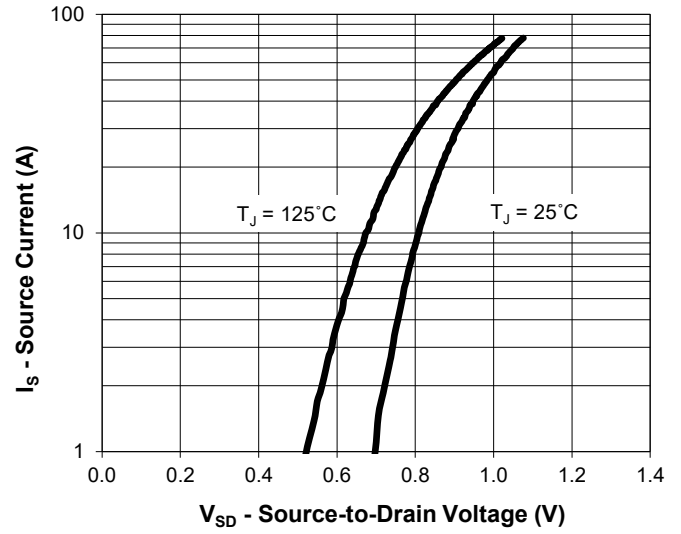
Drain-to-Source Breakdown Voltage vs. Junction Temperature



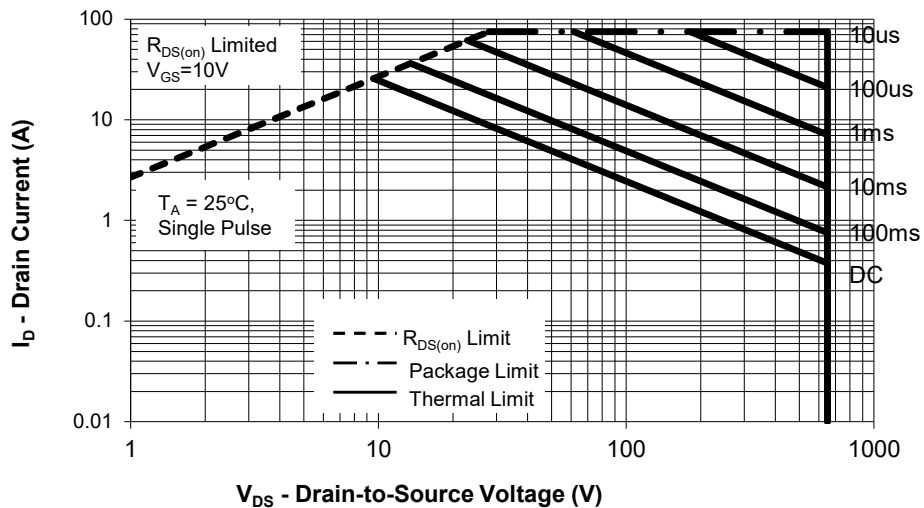
Capacitance



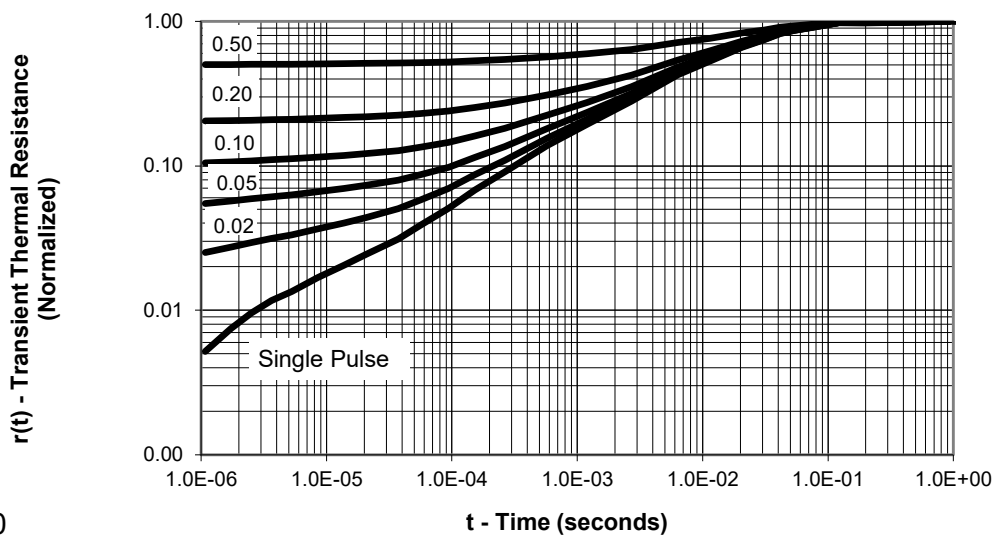
Source-Drain Diode Forward Voltage



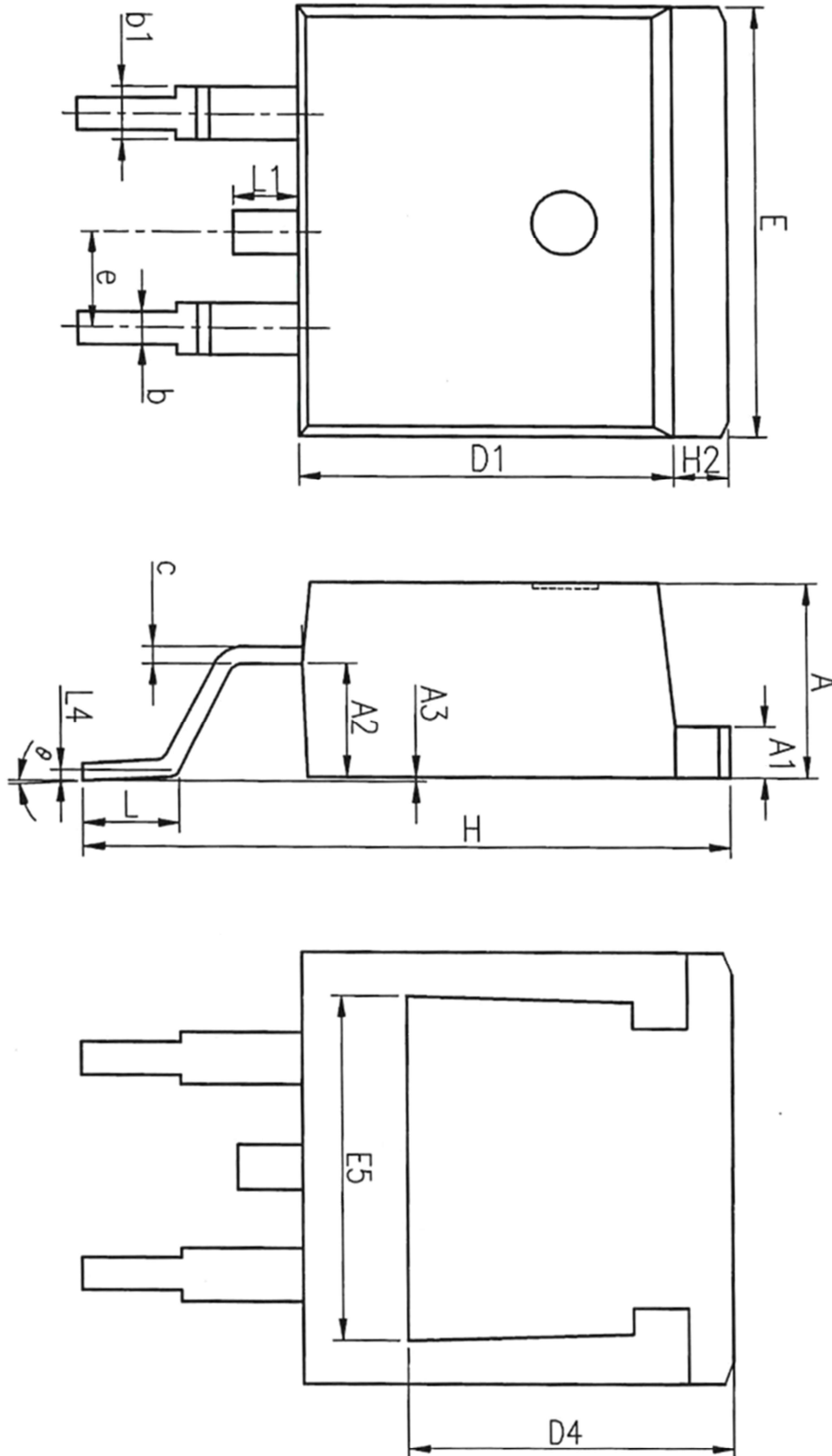
Maximum Rated Forward Biased Safe Operating Area



Transient Thermal Response, Junction-to-Ambient



Package Outline: TO-263(D²PAK)



Package Outline: TO-263(D²PAK)

SYMBOL	MM		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0.00	0.13	0.25
b	0.70	0.81	0.96
b1	1.17	1.27	1.47
c	0.30	0.38	0.53
D1	8.50	8.70	8.90
D4	6.60	-	-
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54 BSC		
H	14.70	15.10	15.50
H2	1.07	1.27	1.47
L	2.00	2.30	2.60
L1	1.40	1.55	1.70
L4	0.25 BSC		
θ	0°	5°	9°

Marking Information

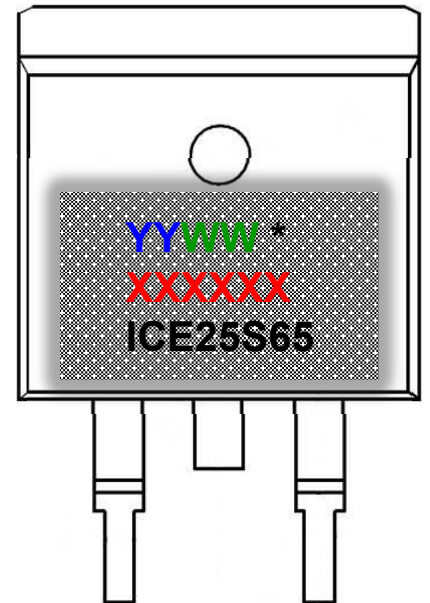
YY = Last two digits of the year

WW = Work week

***** = Site ID

XXXXXX = Lot ID

ICE25S65 = ICE is IceMOS logo and 25S65 is a designated device part number



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